

SOT1381-2

WLCSP6, wafer level chip-size package; 6 terminals; 0.5 mm pitch; 1.39 mm x 0.89 mm x 0.465 mm body

3 March 2022

Package information

1 Package summary

| | |
|---------------------------------------|---------------------------------------|
| Terminal position code | B (bottom) |
| Package type descriptive code | WLCSP6 |
| Package style descriptive code | WLCSP (wafer level chip-size package) |
| Package body material type | P (plastic) |
| Mounting method type | S (surface mount) |
| Issue date | 06-12-2021 |
| Manufacturer package code | 98ASA01834D |

Table 1. Package summary

| Parameter | Min | Nom | Max | Unit |
|--------------------------------|-----|-------|-----|------|
| package length | - | 1.39 | - | mm |
| package width | - | 0.89 | - | mm |
| seated height | - | 0.465 | 0.5 | mm |
| nominal pitch | - | 0.5 | - | mm |
| actual quantity of termination | - | 6 | - | |



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2 Package outline

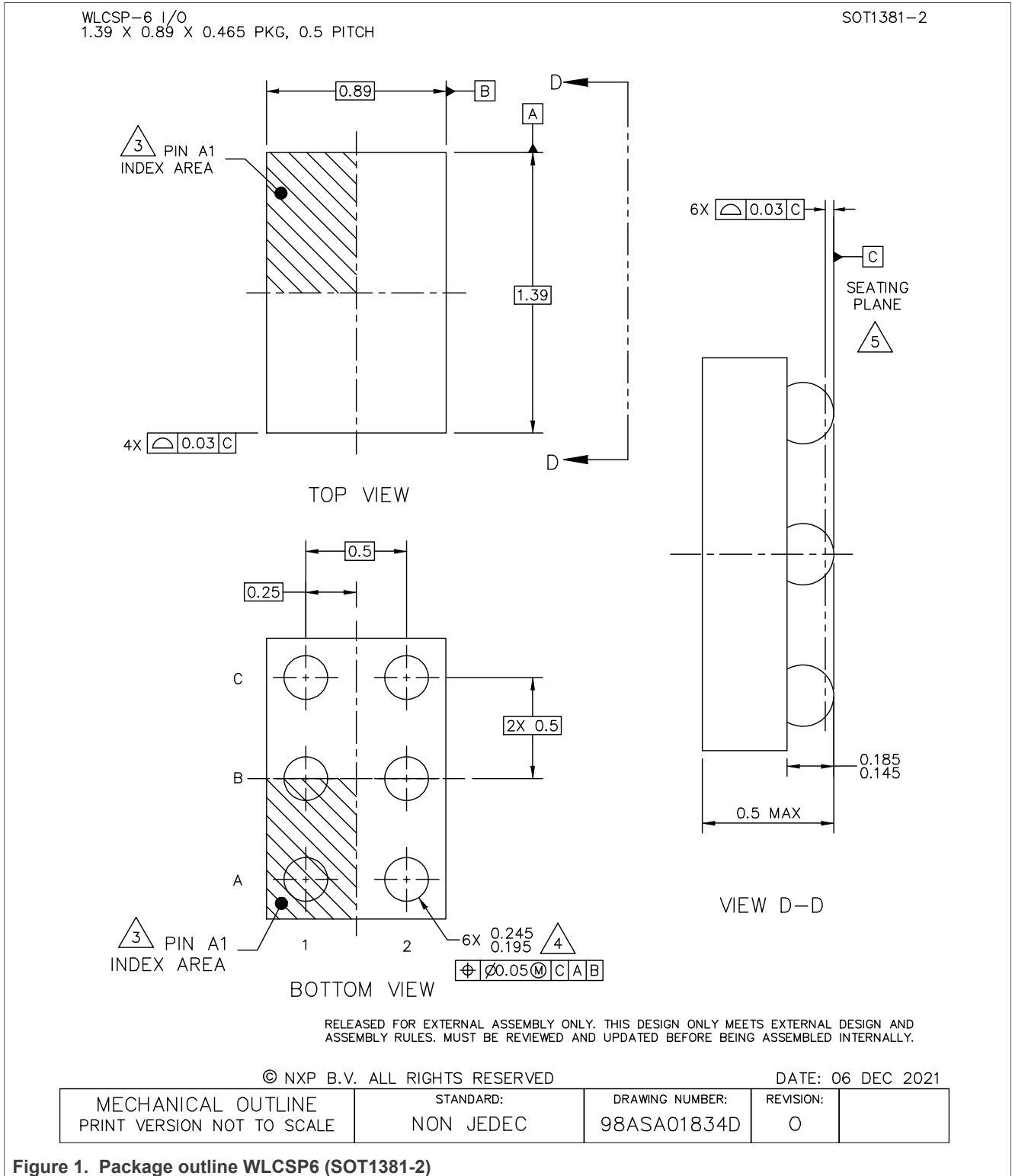
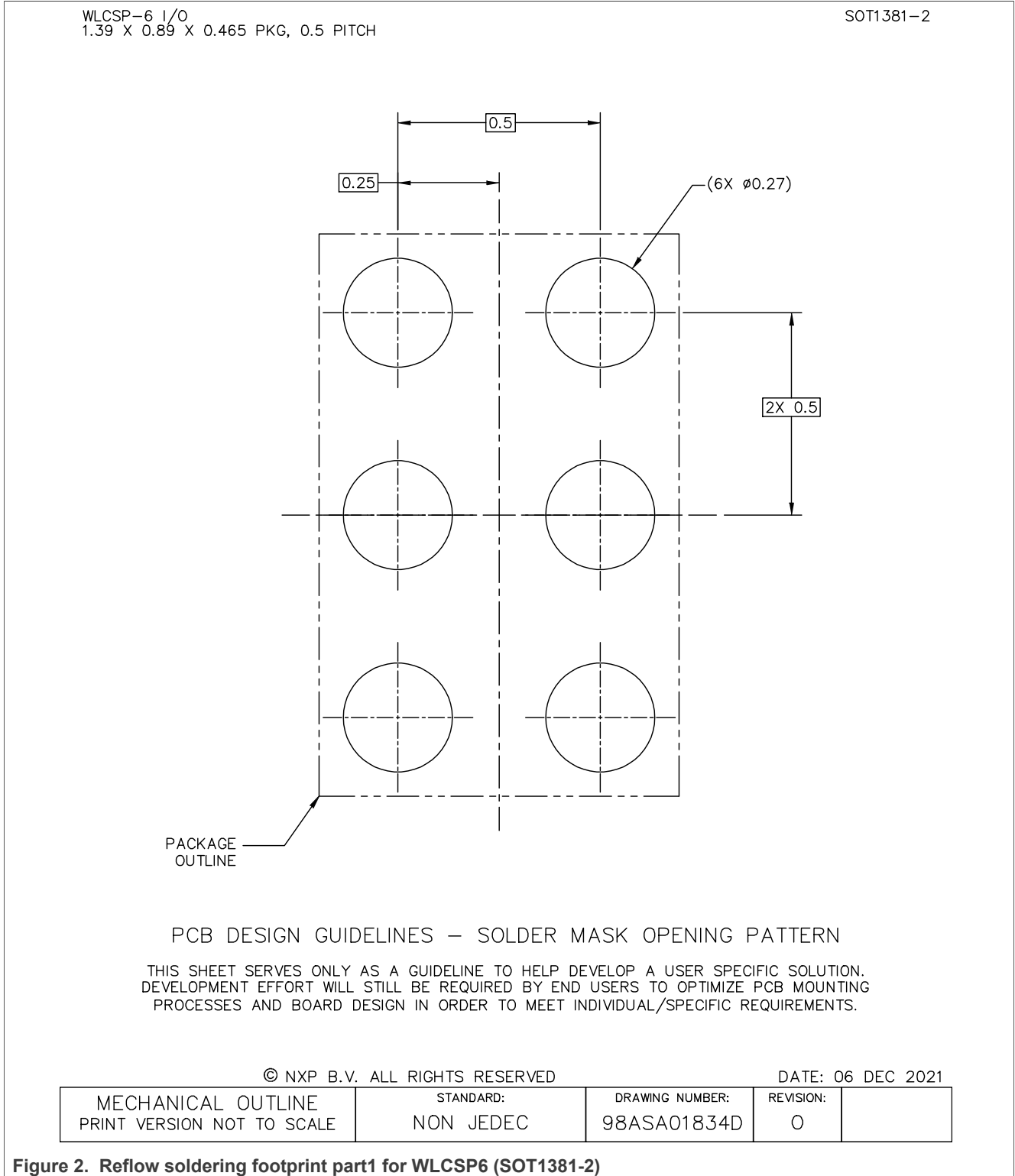


Figure 1. Package outline WLCSP6 (SOT1381-2)

WLCSP6, wafer level chip-size package; 6 terminals; 0.5 mm pitch; 1.39 mm x 0.89 mm x 0.465 mm body

3 Soldering



WLCSP6, wafer level chip-size package; 6 terminals; 0.5 mm pitch; 1.39 mm x 0.89 mm x 0.465 mm body

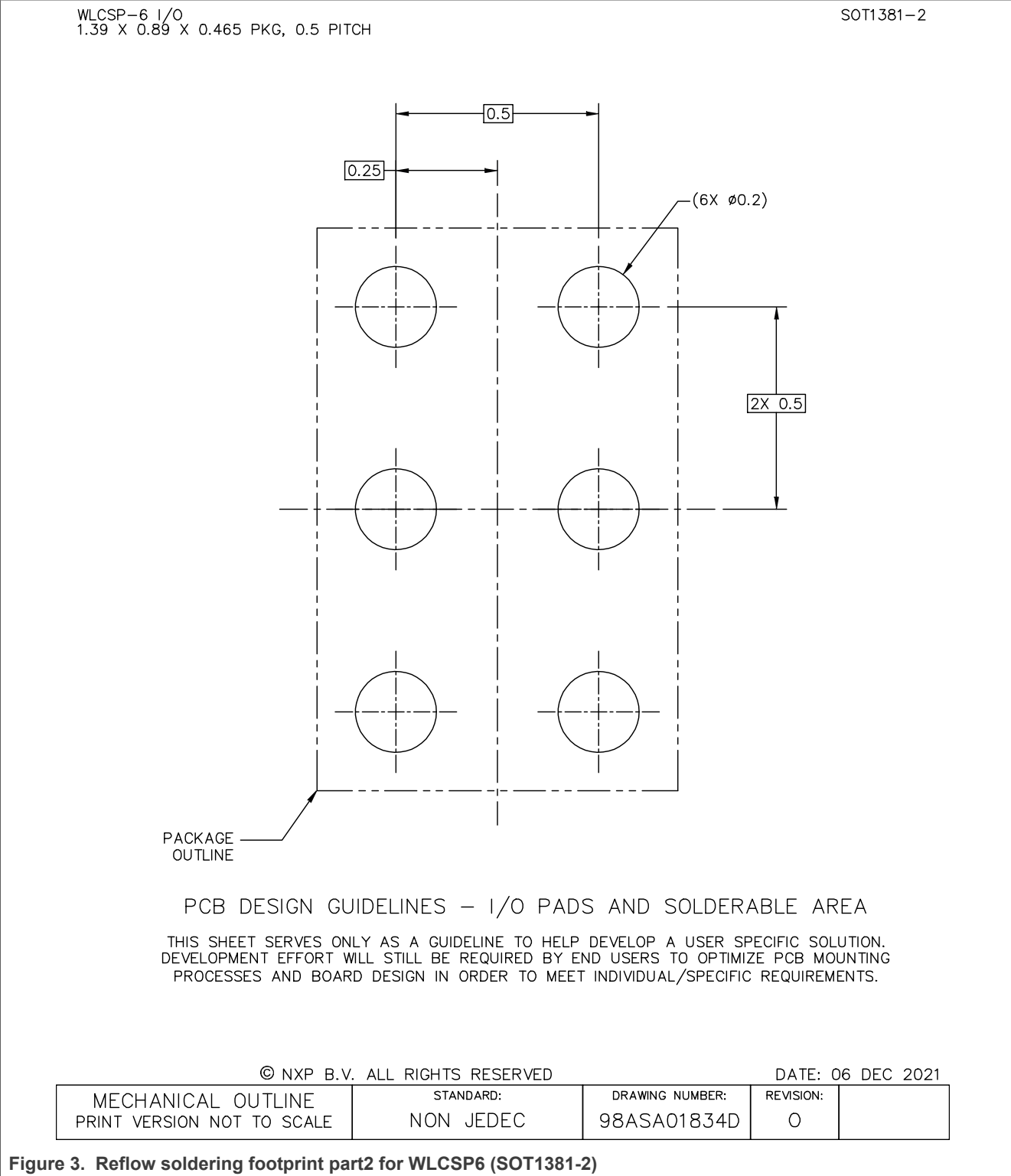


Figure 3. Reflow soldering footprint part2 for WLCSP6 (SOT1381-2)

WLCSP6, wafer level chip-size package; 6 terminals; 0.5 mm pitch; 1.39 mm x 0.89 mm x 0.465 mm body

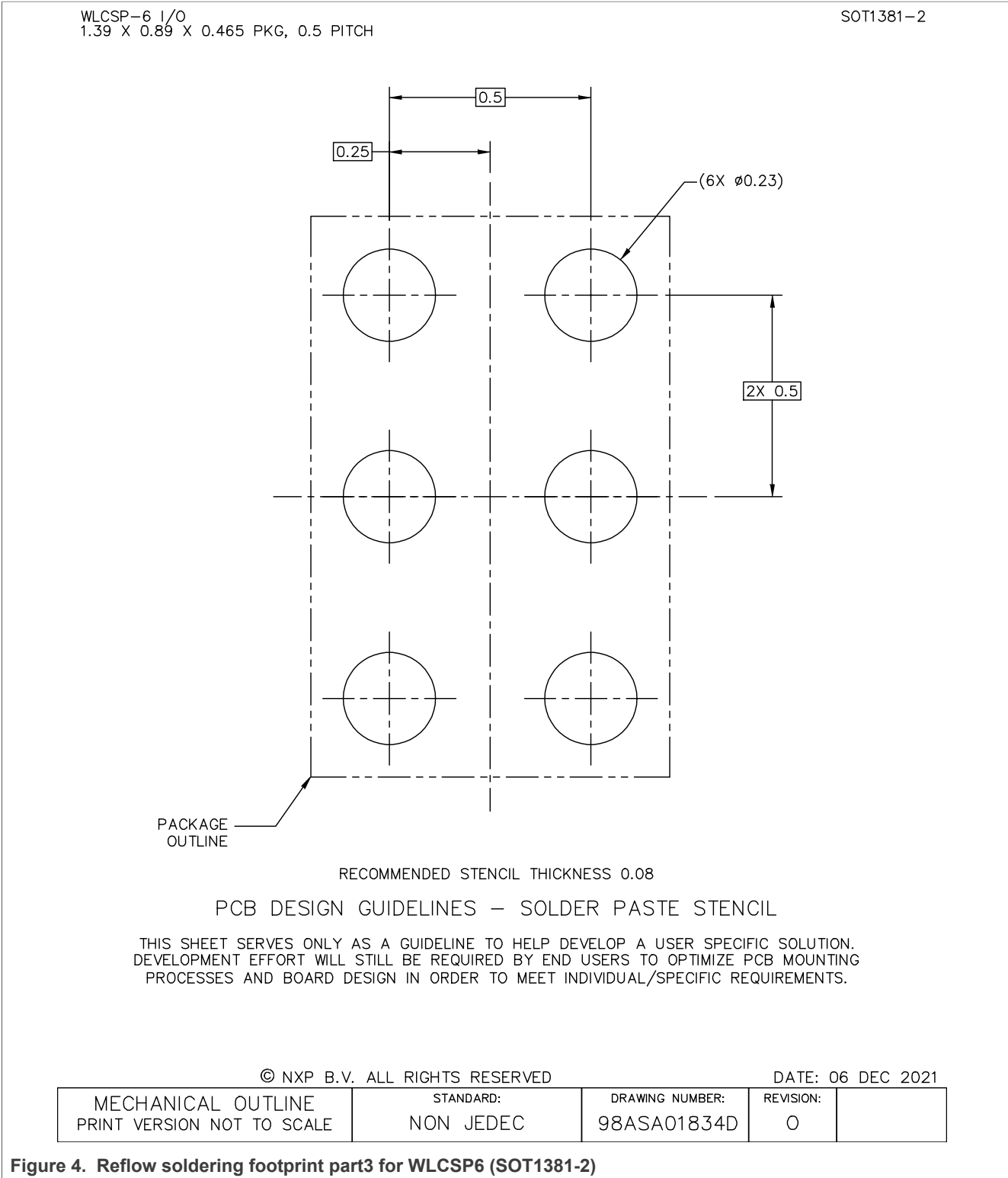


Figure 4. Reflow soldering footprint part3 for WLCSP6 (SOT1381-2)

WLCSP6, wafer level chip-size package; 6 terminals; 0.5 mm pitch; 1.39 mm x 0.89 mm x 0.465 mm body

WLCSP-6 I/O
1.39 X 0.89 X 0.465 PKG, 0.5 PITCH

SOT1381-2

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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DATE: 06 DEC 2021

| | | | | |
|--|------------------------|--------------------------------|----------------|--|
| MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE | STANDARD: NON JEDEC | DRAWING NUMBER: 98ASA01834D | REVISION: 0 | |
|--|------------------------|--------------------------------|----------------|--|

Figure 5. Package outline note WLCSP6 (SOT1381-2)

4 Legal information

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